

ABSTRACT

Provided are a hollow sealing sheet from which a highly reliable hollow package can be produced; and a method for producing a hollow package. The present invention provides a hollow sealing sheet for hollow-sealing an electronic component. The hollow sealing sheet contains a resin, and has a controlled resin ingress property into a hollow part at 40°C or higher and 100°C or lower. When the resin is filled into a molding die having a slit having a width of 20 μm and the resin is pressurized at a pressure of 10 kg/cm² and a temperature of 150°C for 10 minutes, an amount of resin ingress into the slit is preferably 3 mm or less.